# **Colour Television**



# LC 4.7, FM 242 (FTV2.1), FTP 1.1, FTP 2.2 X





**Supplement SDI PDP Repair Manual** 

# Service Manual

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# 1. Technical Specifications

# 1.1 Model / Chassis overview

PDP Type	Model Name	H x V Pixel	Chassis
37"SDv4	S37SD-YD02 (*) S37SD-YB01	852 x 480	LC4.7
42"SDv2	S42SD-YD06 (*) S42SD-YB04	852 x 480	FM242 (FTV2.1) FTP1.1
42"SDv3	S42SD-YD05 (*) S42SD-YB03	852 x 480	LC4.7 FTP2.2x
42"HDv3	S42AX-XD03 (*) S42AX-XB01	1024 x 768	FTP2.2U
50HDv3	S50HW-XD03 (*) S50HW-XB02	1366 x 768	FTP2.2E

(\*) are Model names with PSU, but only PDP model without PSU will be delivered as spare part

# 42" SDv2

# External View

M3 = X Board + Y Board + Logic Board + PSU + SUB PSU



Figure 1-1

# 42" SDv3

# External View

M3 = X Board + Y Board + Logic Board + PSU + SUB PSU



Figure 1-2





Figure 1-3

# 42"HDv3

1.

# **Points of Screw Mount**

# External View

M3 = X Board + Y Board + Logic Board + PSU + SUB PSU



Figure 1-4

**Points of Screw Mount** 



Figure 1-5

# 37" SDv4

External View

M3 = X Board + Y Board + Logic Board + PSU + SUB PSU '





Figure 1-7

# 50" HDv3

# External View

M3 = X Board + Y Board + Logic Board + PSU + SUB PSU



Figure 1-8

# Points of Screw Mount



Figure 1-9

# S/SD/HD 3.1 PDP

# 1.2 Serial Number

1.

# 26.1408.07.0865 Serial No: 0001~9999 Date: 01~31 Month: 01~12 Year: 00(2000) ~99(2099) Line No: 1~9 (0:Pilot Line) Type: 02~48 (ex.50HDv3:26) (Step of even)

# Figure 1-10

# 1.3 Specifications

Ne	ltore		Presidention 27" CDV/	C no.	ification 40" CDV(2 (vmcC)
NO	Item	Specification 37 SDV4		Spec	cilication 42 SDV2 (ypob)
1	Pixel	852 (H) x 480	852 (H) x 480 (V) pixels (1 pixel = 1 R,G,B cells)		O (V) pixels (1 pixel = 1 R,G,B cells)
2	Number of Cells		2556 (H) x 480 (V)		2556 (H) x 480 (V)
3	Pixel Pitch	0.9	60 (H) mm x 0.960 (V) mm	1.0	95 (H) mm x 1.110 (V) mm
4	Cell Pitch	R	0.320 (H) mm x 0.960 (V) mm	R	0.324 (H) mm x 1.110 (V) mm
		G	0.320 (H) mm x 0.960 (V) mm	G	0.365 (H) mm x 1.110 (V) mm
		В	0.320 (H) mm x 0.960 (V) mm	В	0.406 (H) mm x 1.110 (V) mm
-	Disalau sina	Horizontal 817.9	Horizontal 817.92mm x Vertical 460.80mm[ 32.30 inch 9		n x 532.800(V) mm[ 36.73 inch x 20.98
э	Display size	x 18.14 inch ]		inch ]	
6	Screen size	Diagonal 37" Color Plasma Display Module		Diagonal 42" Color Plasma Display Module	
7	Screen aspect	16:9			16:9
8	Display color		16.77 million colors		16.77 million colors
9	Viewing angle	Over 160×(Angle with 50% and greater brightness per- pendicular to PDP module)		Over 160×(Ang pe	le with 50% and greater brightness per- endicular to PDP module)
10	Dimensions	982 (W) x 582 (H) x 52.9 (D) mm		982	W) x 582 (H) x 52.9 (D) mm
11	Weight	Module 1	About 15.5 kg	Module 1	About 16.6 kg
12	Broadcasting reception- Vertical frequencyand- Video/Logic Interface	PL42SD003C	60Hz/ 50Hz, LVDS	PL42SD003C	60Hz/ 50Hz, LVDS

No	Item	Specification 42" SDV3		
1	Pixel	852 (H) x 480 (V) pixels (1 pixel = 1 R,G,B cells)		
2	Number of Cells		2556 (H) x 480 (V)	
3	Pixel Pitch	1.09	95 (H) mm x 1.110 (V) mm	
4	Cell Pitch	R 0.365 (H) mm x 1.110 (V) mm		
		G	0.365 (H) mm x 1.110 (V) mm	
		В	0.365 (H) mm x 1.110 (V) mm	
5	Display size	932.940 (H) mm x 532.800(V) mm[ 36.73 inch x 20.9		
	-	Inch ]		
6	Screen size	Diagonal 42" Color Plasma Display Module		
7	Screen aspect	16:9		
8	Display color		16.77 million colors	
9	Viewing angle	Over 160×(Angle with 50% and greater brightness per- pendicular to PDP module)		
10	Dimensions	982 (W) x 582 (H) x 52.9 (D) mm		
11	Weight	Module 1	About 16.6 kg	
12	Broadcasting reception- Vertical frequencyand- Video/Logic Interface	PL42SD003C	60Hz/ 50Hz, LVDS	

No	ltem	S	specification 42" HDV3	9	Specification 50" HDV3
1	Pixel	Horizontal 1.024	Horizontal 1.024 xVertical 768 pixels(1 pixel = 1 R,G,B   cells)		6 x Vertical 768 pixels(1 pixel = 1 R,G,B cells)
2	Number of Cells		3072 (H) x 768 (V)	Horizo	ntal 4,098 x Vertical 768 cells
3	Pixel Pitch	Horizor	ntal 912mm x Vertical 693mm	Horizonta	al 810mm x mmVertical 810mm
4	Cell Pitch	R	Horizontal 0.304mm x Vertical 693mm	R	Horizontal 270mm x Vertical 810mm
		G	Horizontal 0.304mm x Vertical 693mm	G	Horizontal 270mm x Vertical 810mm
		В	Horizontal 0.304mm x Vertical 693mm	В	Horizontal 270mm x Vertical 810mm
5	Display size	932.940 (H) mm x 532.800(V) mm[ 36.73 inch x 20.98 inch ]		Horizontal	1106.46mm x Vertical 622.08mm
6	Screen size	Diagonal 42" Color Plasma Display Module		Diagonal	50" Color Plasma Display Module
7	Screen aspect	16:9			16:9
8	Display color		16.77 million colors		16.77 million colors
9	Viewing angle	Over 160×(Angle with 50% and greater brightness per- pendicular to PDP module)		Over 160×(Ang pe	le with 50% and greater brightness per- endicular to PDP module)
10	Dimensions	982 (W) x 582 (H) x 52.9 (D) mm		1184(	W) x 700 (H) x 60.1 (D) mm
11	Weight	Module 1	About 18.0 kg	Module 1	About 18.0 kg
12	Broadcasting reception- Vertical frequencyand- Video/Logic Interface	PL42SD003C	60Hz/ 50Hz, LVDS	PL42SD003C	60Hz/ 50Hz, LVDS

# Safety Instructions, Warnings and Notes 2.

\*\* To prevent the risks of unit damage, electrical shock and radiation, take the following safety, service, and ESD precautions.

### 2.1 Safety instructions

2.

It is not allowed to operate the FTV-set without glass plate. One function of this glass plate is to absorb Infrared Radiation. Without this glass plate the level of Infrared Radiation produced by the plasma display could damage your eyes.

1. Safety regulations require that during a repair:

- the set should be connected to the mains via an isolating transformer ( in this particular case a transformer of  $\geq$  800 VA);
- safety components, indicated by the symbol should be replaced by components identical to the original ones;
- 2. Safety regulations require that after a repair the set must be returned in its original condition. In particular attention should be paid to the following points.
  - Note: The wire trees should be routed correctly and fixed with the mounted cable clamps.
  - The insulation of the mains lead should be checked for external damage.
  - The electrical DC resistance between the mains plug and the secondary side should be checked (only for sets that have mains isolated power supply). This check can be done as follows:
  - unplug the mains cord and connect a wire between the two pins of the mains plug;
  - set the mains switch to the on position (keep the mains cord unplugged!);
  - measure the resistance value between the pins of the mains plug and the metal shielding of the tuner or the aerial connection on the set. The reading should be between 4.5 M $\Omega$  and 12 M $\Omega$ ;
  - switch off the TV and remove the wire between the two pins of the mains plug.
  - The cabinet should be checked for defects to avoid touching of any inner parts by the customer.

### 2.2 Warnings

1. ESD 🚣

All ICs and many other semiconductors are susceptible to electrostatic discharges (ESD 🖾). Careless handling during repair can reduce life drastically. When repairing, make sure that you are connected with the same potential as the mass of the set by a wristband with resistance. Keep components and tools also at this same potential.

- 2. Available ESD protection equipment:
  - complete kit ESD3 (combining all 6 prior products small table mat) 4822 310 10671
  - wristband tester 4822 344 13999
- 3. Never replace modules or other components while the unit is switched on.
- When making settings, use plastic rather than metal tools. This will prevent any short circuits and the danger of a circuit becoming unstable.

### 2.3 Handling Precautions for Plasma Display

- PDP module use high voltage that is dangerous to human. Before operating PDP, always check the dust to prevent short circuit. Be careful touching the circuit device when power is on.
- PDP module is sensitive to dust and humidity. Therefore, assembling and disassembling must be done in no dust place.

- PDP module has a lot of electric devices. Service engineer must wear equipment(for example, earth ring) to prevent electric shock and working clothes to prevent electrostatic.
- PDP module use a fine pitch connector which is only working by exactly connecting with flat cable. Operator must pay attention to a complete connection when connector is reconnected after repairing.
- The capacitor's remaining voltage in the PDP module's circuit board temporarily remains after power is off. Operator must wait for discharging of remaining voltage during at least 1 minute.

### 2.4 Safety Precautions for Service (Handling, prevention of a electrical shock)

# 2.4.1 (Safety Precautions)

- Before replacing a board, discharge forcibly
- The remaining electricity from board.
- When connecting FFC and TCPs to the module, recheck that they are perfectly connected.
- To prevent electrical shock, be careful not to touch leads during circuit operations.
- To prevent the Logic circuit from being damaged due to wrong working, do not connect/disconnect signal cables during circuit operations.
- Do thoroughly adjustment of a voltage label and voltageinsulation.
- Before reinstalling the chassis and the chassis assembly, be sure to use all protective stuffs including a nonmetal controlling handle and the covering of partitioning type.
- Caution for design change : Do not install any additional devices to the module, and do not change the electrical circuit design.
- For example: Do not insert a subsidiary audio or video connector. If you insert It, It cause danger on safety. And, If you change the design or insert, Manufactor guarantee will be not effect. .
- If any parts of wire is overheats of damaged, replace it with a new specified one immediately, and identify the cause of the problem and remove the possible dangerous factors.
- Examine carefully the cable status if it is twisted or damaged or displaced. Do not change the space between parts and circuit board. Check the cord of AC power preparing damage.
- Product Safety Mark: Some of electric or implement material have special characteristics invisible that was related on safety. In case of the parts are changed with new one, even though the Voltage and Watt is higher than before, the Safety and Protection function will be lost.
- The AC power always should be turned off, before next repair..
- Check assembly condition of screw, parts and wire arrangement after repairing. Check whether the material around the parts get damaged.

# 2.4.2 (Precaution when repairing ESD)

- There is ESD which is easily damaged by electrostatics.(for example Integrated circuit, FET) Electrostatic damage rate of product will be reduced by the following technics
- Before handling semiconductor parts/assembly, must remove positive electric by ground connection, or must wear the antistatic wrist-belt and ring. (It must be operated after removing dust on it - It comes under precaution of electric shock.)

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2.

- After removing ESD assembly, put on it with aluminum stuff on the conductive surface to prevent charging.
- Do not use chemical stuff using Freon. It generates positive electric that can damage ESD.
- Must use a soldering device for ground-tip when soldering or de-soldering ESD.
- Must use anti-static solder removal device. Most removal device do not have antistatic which can charge a enough positive electric enough damaging ESD.
- Before removeing the protective material from the lead of a new ESD, bring the protective material into contact with the chassis or assembly that the ESD is to be installed on.
- When handing an unpacked ESD for replacement, do not move around too much. Moving (legs on the carpet, for example) generates enough electrostatic to damage the ESD.
- Do not take a new ESD from the protective case until the ESD is ready to be installed. Most ESD have a lead, which is easily short-circuited by conductive materials (such as conductive foam and aluminum)

# 2.5 Notes

A glass plate is positioned before the plasma display. This glass plate can be cleaned with a slightly humid cloth. If due to circumstances there is some dirt between the glass plate and the plasma display panel it is recommended to do some maintenance by a qualified service employee only.

### 2.5.1 Notes on safe handling of the plasma display

### Notes to follow during service

- The work procedures shown with the Note indication are important for ensuring the safety of the product and the servicing work. Be sure to follow these instructions.
- Before starting the work, secure a sufficient working space.
- At all times other than when adjusting and checking the product, be sure to turn OFF the main POWER switch and disconnect the power cable from the power source of the display (jig or the display itself) during servicing.
- To prevent electric shock and breakage of pwb, start the servicing work at least 30 seconds after the main power bas been turned off. Especially when installing and removing the power supply pwb and the SUS pwb in which high voltages are applied, start servicing at least 2 minutes after the main power bas been turned off.
- While the main power is on, do not touch any parts or circuits other than the ones specified. The high voltage power supply block within the PDP module has a floating ground. If any connection other than the one specified is made between the measuring equipment and the high voltage power supply block, it can result in electric shock or activation of the leakage-detection circuit breaker.
- When installing the PDP module in, and removing it from the packing carton, be sure to have at least two persons
- perform the work white being careful to ensure that the flexible printed-circuit cable of the PDP module does not
- get caught by the packing carton.
- When the surface of the panel comes into contact with the cushioning materials, be sure to confirm that there is no foreign matter on top of the cushioning materials before the surface of the panel comes into contact with the cushioning materials. Failure to observe this precaution may result in, the surface of the panel being scratched by foreign matter.
- When handling the circuit pwb, be sure to remove static electricity from your body before handling the circuit pwb.
- Be sure to handle the circuit pwb by holding the large parts as the heat sink or transformer. Failure to observe this precaution may result in the occurrence of an abnormality in the soldered areas.
- Do not stack the circuit pwb. Failure to observe this precaution may result in problems resulting from scratches on the parts, the deformation of parts, and short-circuits due to residual electric charge.

- Routing of the wires and fixing them in position must be done in accordance with the original routing and fixing configuration when servicing is completed. All the wires are routed far away from the areas that become hot (such as the heat sink). These wires are fixed in position with the wire clamps so that the wires do not move, thereby ensuring that they are not damaged and their materials do not deteriorate over long periods of time. Therefore, route the cables and fix the cables to the original position and states using the wire clamps.
- Perform a safety check when servicing is completed. Verify that the peripherals of the serviced points have not undergone any deterioration during servicing. Also verify that the screws, parts and cables removed for servicing purposes have all been returned to their proper locations in accordance with the original

# **Directions For Use** 3.

Not applicable

# **Mechanical Instruction** 4.

### 4.1 **Disassembling / Re-asssembling**

- 4.1.1 Disassembling & Re-assembling of FPC (Flexible Printed Circuit) and Y-Buffer (Upper and Lower)
  - 1. Removal procedure



- Pull out the FPC from Connector by holding the lead of the • FPC with both hands.
- 2. Assembling procedures



Push the lead of FPC with same force on both sides into the connector.

Notice: Be careful do not get a damage on the connector pin during connecting by mistake.

# 4.1.2 Assembling & Disassembling of Flat Cable Connector of X-main Board

# 1. Disassembling Procedure



- Pull out the clamp of connector.
- Pull Flat cable out press down lightly.
- Turn the Flat cable reversely.













2. Assembling Procedures





- Put the Flat cable into the connector press down lightly until locking sound ("Click.") comes out.
- 4.1.3 Assembling & Disassembling the FFC and TCP form Connector

# 1. Disassembling of TCP

•



• Open the clamp carefully.

• Pull the TCP out from connector.

2. Assembling of TCP



- Put the TCP into the Connector carefullyClose the clamp completely.
- (The sound "Click." comes out.)

# Notice:

- 1) Checking whether the foreign material is on the Connector inside before assembling of TCP.
- 2) Be careful do not get a damage on the board by ESD during handling of TCP.



3. Misassembling of TCP



• The misassembling of TCP is the cause of defect.

# 4. Assembling & Disassembling of FFC

The procedure of assembling and disassembling of FFC is same as TCP



• This is the photo of the assembling of FFC.

# 4.1.4Exchange of LBE, LBF, LBG board

Photo 1



EN 12 4. S/SD/HD 3.1 PDP Mechanical Instruction

Photo 2 - 42" SDv2



Photo 2 - 42" SDv3





Photo 2 - S37" SDv4



EN 14 4. S/SD/HD 3.1 PDP

Photo 2 - 50" HDv3



- 1. 42" SDv3 Remove the screws in order of 2-3-5-7-1-4-6 and 10-11-13-16-9-12-14 for HD from heat sink and then get rid of heat sink. (Photo 1)
  - 42" HDv3, S37" SDv4, 50" HDv3

- Remove the screws in order of Center - Left Side - Right

- Side from heat sink and then get rid of heat sink. (Photo 1)
- 2. Remove the TPC, FFC and power cable from the connectors.
- 3. Remove all the screws from defected board.
- 4. Remove the defected board.
- 5. Replace the new board and then screw tightly.
- 6. Get rid of the foreign material from the connector.
- 7. Connect the TCP, FFC and power cable to the connector.
- 8. Reassemble the TCP heat sink.
- 42" SDv3 Screw in order of 4-1-7-6-5-3-2 and 12-9-15-14-13-11-10 for HD. (Photo 2) 42" HDv3, S37" SDv4, 50" HDv3 - Screw in order of Right Side - Left Side - Center (Photo 2)

If you screw too tightly, it is possible to get damage on the Driver IC of TCP.

# 4.1.5 Exchange YBU, YBL and YM board

- 1. Separate all the FPC connector of YBU (Y-Buffer upper) and YBL (Lower). (Photo 1)
- 2. Separate all the connector of CN5001 and CN5008 from Y-Main.
- 3. Loosen all the screws of YBU, YBL and YM.
- 4. Remove the board from chassis.
- 5. Remove the connector of CN5006 and CN5007 among YBU, YBL and YM.
- $\mbox{6. Remove the YBL and YBU from Y-main.}$
- 7. Replace the defected board.

4.





- 11. Connect the FPC and YM of panel to the connector.
- 12. Supply the electric power to the module and then check the waveform of board.
- 13. Turn off the power after the waveform is adjusted.



10. Arrange the board on the chassis and then screw to fix.





# 5. Diagnostic software

# 5.1 Repair tools

1.) 3122 785 90581 = Foam buffers			
2.) Compair connector:	3122 785 90800		
3.) V2 jig	3122 785 90760		
4.) V3 jig	3122 785 90770		



Figure 5-1 Foam buffers for PDP



Figure 5-2 3122 785 90760



Figure 5-3 3122 785 90770

# 5.2 Repair Scenario

# Repair Scenario FTV with SDI PDP











Repair Scenario SDI PDP panels as stand alone







Figure 5-8



**Diagnostic software** 

5.

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S/SD/HD 3.1 PDP

Diagnostic software

No Display



Abnormal Display





Some horizontal lines don't exist on the Display. Sustain open or short



# Some Vertical Lines don't exists or are always on, Adress Open or Adress Short. A part of the Display is not addressed



# 6. Block Diagrams, Testpoint Overview, and Waveforms

# 6.1 Block Diagram for Logic circuit



42" SDv3



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6.



### 6.2 **PSU Board diagram**

42" SDv2



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6.

No	Output voltage(V)	Voltage Setting (Nominal Load $\lambda$ )	Output Voltage Variable Point
1	PFC		370V ~ 400V
2	VS		160V ~ 185V
3	VA		65V ~ 80V
4	VE		150V ~ 170V
5	VSET	Check voltage label on the PDP for correct values.	160V ~ 180V
6	VSCAN		-55V ~ -75V
7	D5VL		4.0V ~ 6.0V
8	D3V3		2.8V ~ 4.0V
9	VCC		Fixed
10	5V2		3.5V ~ 6.0V
11	9V_Standby		Fixed



No	Output voltage(V)	Voltage Setting (Nominal Load $\lambda$ )	Output Voltage Variable Point
2	VS		160V ~ 185V
3	VA		60V ~ 80V
4	VE		165V ~ 195V
5	VSET	Check voltage label on the PDP for	160V ~ 180V
6	VSCAN	correct values.	-145V ~ -175V
7	D5VL		5.0V ~ 6.0V
8	D3V3		2.8V ~ 3.8V
9	VCC		Fixed
10	5V2		4.5V ~ 5.6V
11	9V_Standby		Fixed



No	Output voltage(V)	Voltage Setting (Nominal Load $\lambda$ )	Output Voltage Variable Point
1	PFC		370V ~ 400V
2	VS		160V ~ 185V
3	VA		65V ~ 80V
4	VE		150V ~ 170V
5	VSET	Check voltage label on the PDP for correct values.	160V ~ 180V
6	VSCAN		-55V ~ -75V
7	D5VL		4.0V ~ 6.0V
8	D3V3		2.8V ~ 4.0V
9	VCC		Fixed
10	5V2		3.5V ~ 6.0V
11	9V_Standby		Fixed

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7.

# **Circuit Diagrams and PWB Layouts** 7.

Not aplicable.

# 8. Aligments

- 8.1 Adjustment Specification, Checking Position etc.
- 8.1.1 42" SDv2



[Picture 1] Waveform of X-Board, Y-Board

# How to adjust waveform



### 42" SDv3 812

# **Procedure**

- 1) Make Full White on Screen.
- 2) Observe waveform using Oscilloscope.
- ① check OUT4 TP in Y-buffer(upper). Observe the waveform of the third waveform of 1TV-Field.
- <sup>②</sup> Adjust the division of oscilloscope like the left picture
- ③ Adjust the period of Vset as 10µS,
  - that of -Vsc(1) as 20µs, that of -Vsc(2) as 5µs, turning VR (Variable Resistor) (only,when you adjust each period of -Vsc(1) & -Vsc(2) adjust Vertical Division of oscilloscope as '2V or 5V')
- ④ VR for Vset : VR5003 (Y\_main) VR for -Vsc(1) : VR5001 (Y\_main)
  - VR for -Vsc(2) : VR5002 (Y\_main)







\* Pay close attention to above adjustment

# \* Dip Switch Mode

# Internal















\* Pay close attention to above adjustment

# \* Dip Switch Mode

Internal



External



# 8.1.4 S37" SDv4





\* Pay close attention to above adjustment

# \* Dip Switch Mode

# Internal



External











EN 42 8. S/SD/HD 3.1 PDP Aligments



\* Pay close attention to above adjustment

# \* Dip Switch Mode

Internal



External



# Aligments S/SD/HD 3.1 PDP 8. EN

# 8.2 Adjusting procedure

# 42" SDv3 (SDv2)

- 1. Get Pattern to be Full White.
- 2. Adjust Vsch to 40V with VR5004.
- 3. Check the waveform with an Oscilloscope.
  - Triggering through V-sync of LOGIC Board.
    - Connect the OUT 4 Test Point at the center of Y\_buffer to other channel, and then check the first SF operating waveform of 1TV-Field.
  - Check the waveform as before by adjusting Horizontal Division. Check the Reset waveform when the V TOGG Level is changed.
  - Set the Vset to 10µsby adjusting VR5002.
  - Set the Falling maintenance time to 30µs by adjusting R5003.
  - Change the waveform position of Oscilloscope to 3SF and then set the Falling maintenance time to 30µsby adjusting the VR5001. GND maintenance section should be checked after the Vertical Division is readjusted to '2V or 5V'.

**Special Notice:** When you adjust the inclination of waveform, do check and adjustment being based on the Reset waveform of 1st Sub-field of 1st Frame and then move to 3rd Sub-field for adjusting.

# 42" HDv3

- 1. Get Pattern to be Full White.
- 2. Adjust Vsch to Clock-wise max by using VR5004 (Vsch should be connected to "+" unit of DMM).
- 3. Check the waveform using Oscilloscope.
  - Triggering through V\_TOGG of LOGIC Board.
  - Connect the OUT 4 Test Point at the center of Y\_buffer to other channel, and then check the first SF operating waveform of 1TV-Field.
  - Check the waveform as before by adjusting Horizontal Division. Check the Reset waveform when the V\_TOGG Level is changed.
  - Set the Vset to 20µs by adjusting VR5002. GND maintenance section should be checked after the Vertical Division is readjusted to '2V or 5V'.
  - Set the Falling maintenance time to 20µs by adjusting R5006.
  - Change the waveform position of Oscilloscope to 3SF and then set the Falling maintenance time to 10µs by adjusting the VR5003. GND maintenance section should be checked after the Vertical Division is readjusted to '2V or 5V'.

**Special Notice:** When you adjust the inclination of waveform, do check and adjustment being based on the Reset waveform of 1st Sub-field of 1st Frame and then move to 3rd Sub-field for adjusting.

# S37" SDv4

- 1. Get Pattern to be Full White.
- Adjust Vsch to 40V by using VR5004 (Vsch should be connected to "+" unit of DMM). Vsch is over 95V than Vsc\_I.
- 3. Check the waveform using Oscilloscope.
  - Triggering through V\_TOGG of LOGIC Board.
  - Connect the OUT 4 Test Point at the center of Y\_buffer to other channel, and then check the first SF operating waveform of 1TV-Field.
  - Check the waveform as before by adjusting Horizontal Division. Check the Reset waveform when the V\_TOGG Level is changed.
  - Set the Vset to 40µs by adjusting VR5001. GND maintenance section should be checked after the Vertical Division is readjusted to '2V or 5V'.
  - Set the Falling maintenance time to 16µs by adjusting R5002.

Change the waveform voltage GND to 38V by adjusting the VR5000.

Special Notice: When you adjust the inclination of waveform, do check and adjustment being based on the Reset waveform of 1st Sub-field of 1st Frame and then move to 3rd Sub-field for adjusting.

# 50" HDv3

- 1. Get Pattern to be Full White.
- Adjust Vsch to 25V by using VR5901\_VSC\_h (Vsc\_h should be connected to "+" unit of DMM).
- 3. Check the waveform using Oscilloscope.
  - Triggering through V\_TOGG of LOGIC Board.
    - Connect the OUT 4 Test Point at the center of Y\_buffer to other channel, and then check the first SF operating waveform of 1TV-Field.
  - Check the waveform as before by adjusting Horizontal Division. Check the Reset waveform when the V TOGG Level is changed.
  - Set the Rising Ramp Flat Time to 50µs by adjusting VR5000. GND maintenance section should be checked after the Vertical Division is readjusted to '2V or 5V'.
  - Set the Falling maintenance time to 35µs by adjusting R5001.
  - Change the waveform position of Oscilloscope to 3SF and then set the Falling maintenance time to 20µs by adjusting the VR5002.
  - GND maintenance section should be checked after the Vertical Division is readjusted to '2V or 5V'.

**Special Notice:** When you adjust the inclination of waveform, do check and adjustment being based on the Reset waveform of 1st Sub-field of 1st Frame and then move to 3rd Sub-field for adjusting.

# Alignment table Y PWB

	Wave Form	Adjusting Location No	Default
37SDV4	Rising_Ramp	VR5001	30 µs (30 ~ 40)
	Falling_Ramp_1st	VR5002	16 µs (10 ~ 20)
	Vsch	VR5000	38V
42SDV2	Rising_Ramp (Vset)	VR5003	10 µs
	-Vsc 1	VR5001	20 µs
	-Vsc 2	VR5002	5 µs
42SDV3	Rising_Ramp	VR5002	10 µs
	Falling_Ramp_1st	VR5003	30 µs
	Falling_Ramp_3rd	VR5001	30 µs
	Vsch	VR5004	40V
42HDV3	Rising_Ramp	VR5002	10 µs
	Falling_Ramp_1st	VR5003	20 µs
	Falling_Ramp_3rd	VR5001	10 µs
	Vsch Scan high volt- age	VR5004	40V
50HDV3	Rising_Ramp	VR5000	50 µs
	Falling_Ramp_1st	VR5001	35 µs
	Falling_Ramp_3rd	VR5002	20 µs
	Vsch Scan high volt- age	VR5901	25V

### **Circuit Descriptions** 9

### Main function of Each Assembly 9.1

### 911 X-main board

The X-main board generate a drive signal by switching the FET in synchronization with logic main board timing and supplies the X electrode of the panel with the drive signal through the

connector.

- 1. Maintain voltage waveforms (including ERC)
- Generate X rising ramp signal 2
- Maintain Ve bias between Scan intervals 3.

### 9.1.2 Y-main board

The Y-main board generate a drive signal by switching the FET in synchronization with the logic

Main Board timing and sequentially supplies the Y electrode of the panel with the drive signal

through the scan driver IC on the Y-buffer board. This board connected to the panel's

Y terminal has the following main functions.

- 1. Maintain voltage waveforms (including ERC)
- Generate Y-rising Falling Ramp 2.
- Maintain V scan bias 3.

### Logic main board 9.1.3

The logic main board generates and outputs the address drive output signal and the X, Y drive signal by processing the video signals. This Board buffers the address dirve output signal and feeds it to the address drive IC (COF module, video signal- X Y drive signal generation , frame memory circuit / address data rearrangement).

### Logic buffer(E,F) 9.1.4

The logic buffer transmits data signal and control signal.

### Y-buffer board (Upper, Lower) 9.1.5

The Y-buffer board consisting of the upper and lower boards supplies the Y-terminal with scan waveforms. The board comprises 8 scan driver IC's (ST microelectronics STV 7617 : 64 or 65 output pins), but 4 ICs for the SD class.

### 9.1.6 **AC Noise Filter**

The AC Noise filter has function for removing noise(low Frequency) and blocking surge. It effects Safety standards (EMC,EMI).

### TCP( Tape Carrier Package ) 9.1.7

The TCP applies Va pulse to the address electrode and constitutes address discharge by the potential difference between the Va pulse and the pulse applied to the Y electrode. The TCP comprise 4 data driver Ics(STV7610A :96 pins output pins) 7 TCPs are required for signal scan.

TCP	Tape Carrier Package
FFC	Flat Foil Cable (connection)
COF	Circuit on Foil
FPC	Flexible Printed Circuit
Vsc H or Vsc L	V Scan High or Low
SF	Sub Frame
Vset RR	Vset Raising Ramp (Flat time)
Vset FR	Vset Falling Ramp (flat time)
VR	Variable resistor
YBU & YBL	
YBM	

### Abbrevitation 9.2

10. Spare Parts List

# 42"SDv2

# PDP type

PDP type			-
S42SD-YD06	9322 195 45682	PDP model name	P
S42SD-YB04	9965 000 17797	PDP without PSU	SE
BOARDS			

LJ92-00632A	9965 000 17726	Logic-Buffer(E)
LJ92-00633A	9965 000 17725	Logic-Buffer(F)
LJ92-00634A	9965 000 17724	Logic-Buffer(G)
LJ92-00751A	9965 000 17727	Y-Buffer(up)
LJ92-00750A	9965 000 17728	Y-Buffer(down)
LJ92-00818A	9965 000 17729	Logic-Board
LJ92-00998A	9965 000 17720	X-Board
LJ92-00999A	9965 000 17731	Y-Board
LJ44-00049A	9965 000 17730	SMPS(PSU)

# 42"SDv3

PDP type		
S42SD-YD05	9322 215 27682	PDP model name
S42SD-YB03	9965 000 25997	PDP without PSU

# BOARDS

LJ92-00811A	9965 000 25109	Logic-Buffer(E)
LJ92-00812A	9965 000 25110	Logic-Buffer(F)
LJ92-00813A	9965 000 25111	Logic-Buffer(G)
LJ92-00796A	9965 000 25112	Y-Buffer(up)
LJ92-00797A	9965 000 25113	Y-Buffer(down)
LJ92-00975D	9965 000 25114	Logic-Board
LJ92-00943A	9965 000 25115	X-Board
LJ92-00944B	9965 000 25116	Y-Board
LJ44-00058A	9965 000 25108	SMPS(PSU)
LJ44-00075A	9965 000 25131	SUB PSU

# 37"SDv4

S37SD-YD02 S37SD-YB01	8204 000 77261 9965 000 26018	PDP model name (non spare) PDP without PSU
BOARDS		
LJ92-00976A LJ92-00977A LJ92-01002A	9965 000 26187 9965 000 26188 9965 000 26189	Logic-Buffer(E) Logic-Buffer(F) Logic-Buffer(G)

L032 01002A	2000 000 20100	Logic Dunci (G)
LG92-01022A	9965 000 26190	Y-Buffer(up)
LJ92-01056A	9965 000 26191	Logic-Board
LJ92-01020A	9965 000 26192	X-Board
LJ92-01021A	9965 000 26193	Y-Board
LJ44-00084A	9965 000 26194	SMPS(PSU)
LJ44-00075A	9965 000 25131	SUB PSU

# 42"HDv3 \*not used in Eu sets

# PDP type

S42AX-XD02	9322 215 25682	PDP model name
S42AX-XB01	9965 000 26016	(non spare) PDP without PSU

# BOARDS

LJ92-00895A	9965 000 25101	Logic-Buffer(E)
LJ92-00896A	9965 000 25102	Logic-Buffer(F)
LJ92-00994A	9965 000 25103	Y-Buffer(up)
LJ92-00993A	9965 000 25104	Y-Buffer(down)
LJ92-00990E	9965 000 25105	Logic-Board
LJ92-00980A	9965 000 25106	X-Board
LJ92-00981A	9965 000 25107	Y-Board
LJ44-00058A	9965 000 25108	SMPS(PSU)
LJ44-00075A	9965 000 25131	SUB PSU

50"HDv3		
PDP type		
S50HW-XD03	9322 215 26682	PDP model name
S50HW-XB02	9966 000 26017	(non spare) PDP without PSU
BOARDS		
LJ92-00917A LJ92-00918A LJ92-00920A LJ92-00920A LJ92-00922A LJ92-00821A LJ92-00881A LJ92-008949C LJ92-00959A LJ92-00859A LJ92-00859A LJ92-00853A LJ92-00853A LJ92-00853A LJ92-00853A	9965 000 25117 9965 000 25118 9965 000 25119 9965 000 25120 9965 000 25122 9965 000 25122 9965 000 25123 9965 000 25124 9965 000 25125 9965 000 25127 9965 000 25128 9965 000 25128 9965 000 25129 9965 000 25130 9965 000 26195	Logic-Buffer(E) Logic-Buffer(G) Logic-Buffer(G) Logic-Buffer(H) Logic-Buffer(I) Y-Buffer(up) Y-Buffer(down) Logic-Board SUBL SUBR X-Board Y-Board SMPS(PSU) SUB PSU

